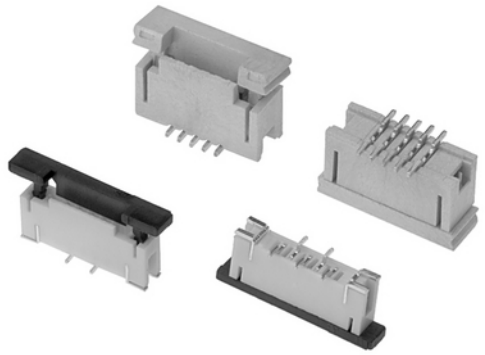
5561

SMT ZIF-Steckverbinder RM 1,00mm, stehend

SMT ZIF-Connectors, 1.00mm Pitch, Vertical

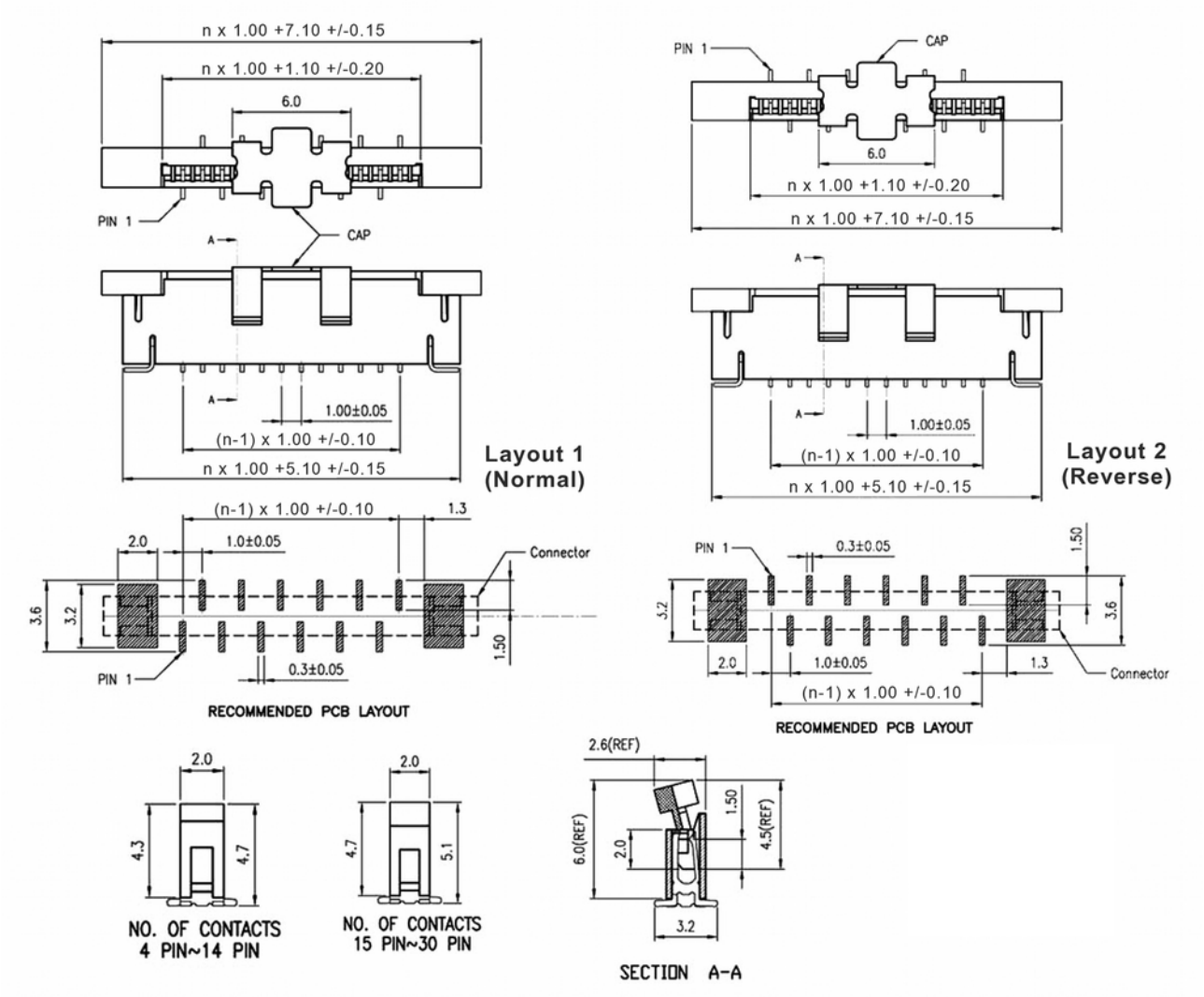
Technische Daten / *Technical Data*

Isolierkörper	Thermoplastischer Kunststoff, nach UL94 V-0
Insulator	*Thermoplastic, rated UL94 V-0*
Kontaktmaterial	Kupferlegierung
Contact Material	*Copper alloy*
Kontaktoberfläche	Verzinnt
Contact Surface	*Tin plated*
Lötbarkeit	IEC 60512-12A
Solderability	*IEC 60512-12A*
Durchgangswiderstand	< 20mΩ
Contact Resistance	*< 20mΩ*
Isolationswiderstand	> 50MΩ
Insulation Resistance	*> 50MΩ*
Spannungsfestigkeit	$250V_{AC}$
Test Voltage	*$250V_{AC}$*
Nennspannung	$50V_{DC}$
Voltage Rating	*$50V_{DC}$*
Nennstrom	0,5A
Current Rating	*0.5A*
Temperaturbereich	-20°C ... +85°C
Temperature Range	*-20°C ... +85°C*
Verarbeitung	Reflow-Lötverfahren
Processing	*Reflow soldering*



© W+P PRODUCTS

Passende Flex-Kabel:
Mate with Flexible Flat Cables:
599



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WEBSITE www.wppro.com

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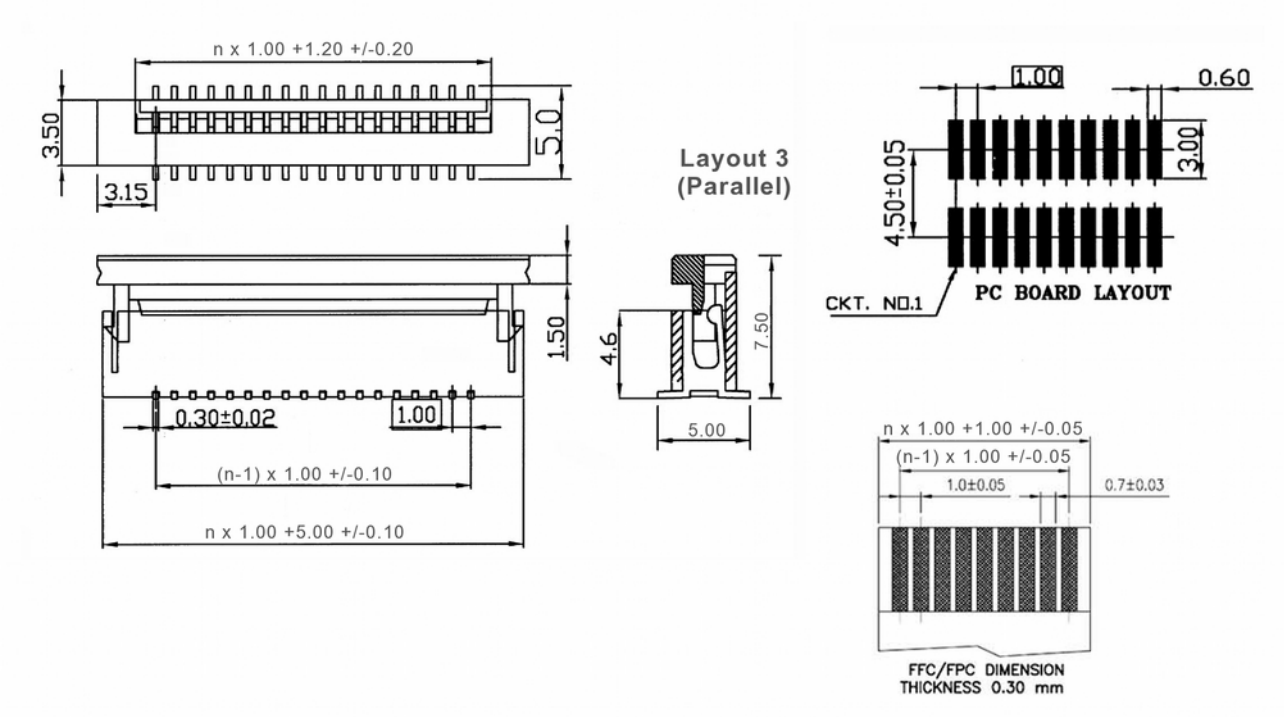
SMT ZIF-Connectors, 1.00mm Pitch, Vertical



Series	*Contacts**	*Layout**	*Packaging**
5561	**20**	**2**	**TR**
	04-30	**1** Normal **2** Reverse **3** Parallel	**ST** **TR**

Lieferformen / *Packaging Options:*
ST In Stangen ohne Pick&Place-Pad / *In tubes w/o Pick&Place-Pad*
TR Tape & Reel / *Tape & Reel*

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
** This is an **order example** -*
please replace by your specifications.

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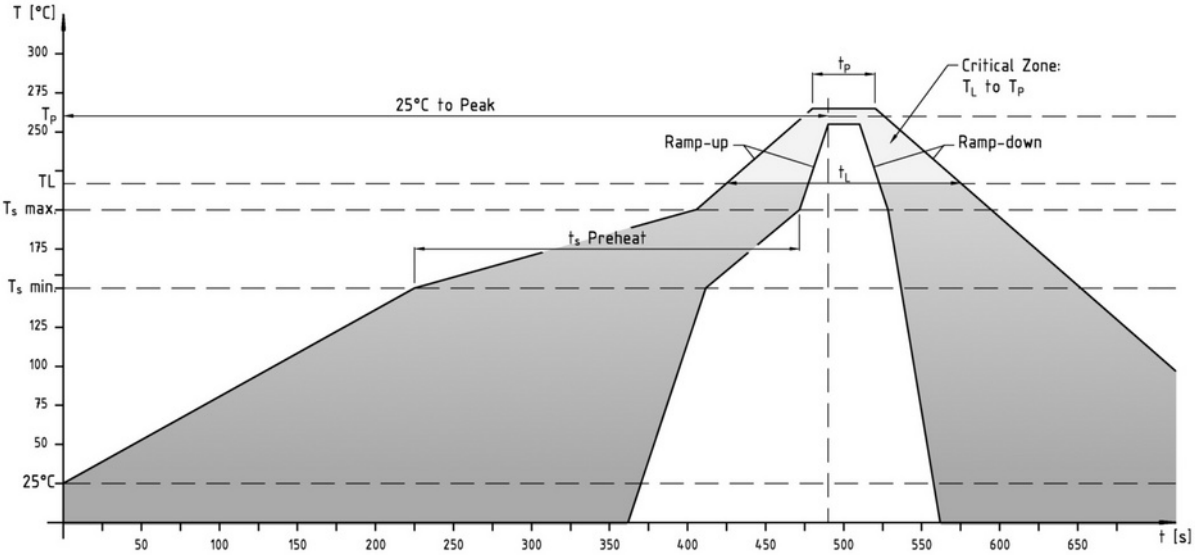
Reflow-Lötempfehlung
Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J_STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_S$min	150°C
Temperatur Maximum $T_S$max	200°C
Dauer $T_S$min - $T_S$max	60-180s
Temperatur Lötbereich T_L	217°C
Verweildauer oberhalb T_L	60-180s
Ramp-Up Rate $T_S$max - T_P	max. 3°C / s
Höchsttemperatur T_P	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_P$max - $T_S$min	6°C / s
Dauer 25°C - Höchsttemperatur T_P	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_S$min	*150°C*
Maximum Temperatur $T_S$max	*200°C*
Duration $T_S$min - $T_S$max	*60-180s*
Soldering Range Temperature T_L	*217°C*
Duration above T_L	*60-180s*
Ramp-Up Rate $T_S$max - T_P	*max. 3°C / s*
Peak Temperature T_P	*260°C ±5*
Duration Peak Temperature	*20-40s*
Ramp-Down Rate $T_P$max - $T_S$min	*6°C / s*
Duration 25°C - Peak Temp. T_P	*Max. 8min*